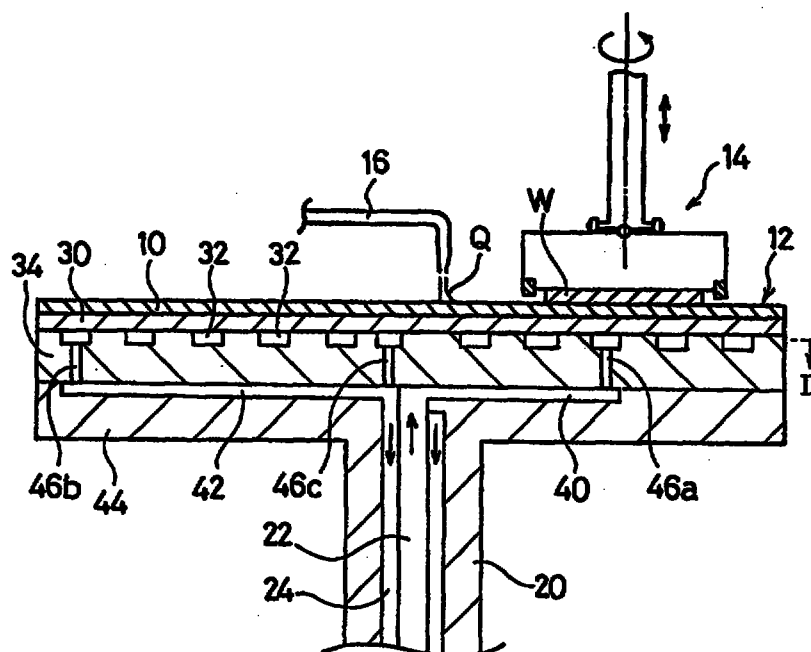




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(54) Title: POLISHING APPARATUS AND POLISHING TABLE THEREFOR



(57) Abstract

A polishing apparatus can strictly control the degree of material removal by providing a close control over the operating temperature in the polishing table (12). The polishing apparatus comprises a polishing table (12) and workpiece holder (14) for pressing a workpiece (W) towards the polishing table (12). The polishing table (12) has a polishing section (30) or a polishing tool attachment section at a surface thereof and a thermal medium passage (32) formed along the surface. The thermal medium passage (32) comprises a plurality of temperature adjustment passages provided respectively in a plurality of temperature adjustment regions which are formed by radially dividing a surface area of the polishing table (12).